

Electronic Patent Application Fee Transmittal

Application Number:	10810965			
Filing Date:	26-Mar-2004			
Title of Invention:	Novel method to improve bump reliability for flip chip device			
First Named Inventor/Applicant Name:	Yen-Ming Chen			
Filer:	Daniel R. McClure			
Attorney Docket Number:	TS01-0413C			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Filing a brief in support of an appeal	1402	1	500	500
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				500